

REMARKS

In the Notice of Allowance mailed September 30, 2005, the Examiner amended the Title of the present application as follows:

MICROFEATURE WORKPIECE PROCESSING APPARATUS AND METHODS
FOR CONTROLLING DEPOSITION OF MATERIALS ON MICROFEATURE
WORKPIECES INCLUDING AFTER PRECURSOR STEP REDUCING THE
PRESSURE IN THE CHAMBER BY AT LEAST 90% DURING PURGING STEP

Applicants respectfully request that the Examiner amend the Title of the present application back to its original form for the following reasons. First, many of the claims do not require reducing the pressure in the chamber after a precursor step. Second, the claims do not recite "reducing the pressure in the chamber by at least 90% during the purging step." For example, claim 1 recites, "reducing pressure within the enclosure to a second enclosure pressure while introducing a flow of a purge gas into the enclosure at a first flow rate, the second enclosure pressure being less than the first enclosure pressure, the processing system having a base pressure at the first flow rate, and a difference between the second enclosure pressure and the first enclosure pressure being at least 90% of the difference between the base pressure and the first enclosure pressure." If the Examiner has any questions, the Examiner is encouraged to call the undersigned representative at (206) 359-6465.

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Respectfully submitted,

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